

Title (en)  
An assembly of an electrical connector and ejector unit for connecting IC cards to printed circuit boards

Title (de)  
Anordnung mit einem elektrischen Verbinder und einer Auswurfvorrichtung zum Verbinden von IC-Karten auf gedruckten Leiterplatten

Title (fr)  
Assemblage d'un connecteur électrique et moyens d'éjection pour connecter des cartes de circuits intégrés sur des plaquettes de circuits imprimés

Publication  
**EP 0595025 B1 19970604 (EN)**

Application  
**EP 93115389 A 19930923**

Priority  
• JP 29332892 A 19921030  
• JP 29332992 A 19921030

Abstract (en)  
[origin: EP0595025A2] An assembly for connecting an IC card to a printed circuit board 38 includes a surface mounted connector 40 and an ejector unit 50. The surface mounted connector 40 has contacts 90, 100 arranged in an upper and a lower row at a narrow pitch to achieve a high degree of density of electronic components while maintaining high accuracy of contact positioning. Contacts 90 are made by punching out from a metal sheet and have round contact sections 92 for electrical connection with an IC card, termination sections 94 with a portion 94a for soldering connection to the printed circuit board, U-shaped retaining sections 96 for insertion into contact holding openings 82 of housing 80 and supporting legs 98 fitted in locking sections 84 of the housing. The ejector unit 50 is small but sufficiently strong and is simple to manufacture. It comprises a frame 54 with left and right edges bent to form a guiding section 60 wrapping around the side edges of the inserted IC card. Retaining members 56, 58 and a grounding contact 64 for the card are also made by the same stamping operation. <IMAGE>

IPC 1-7  
**H01R 23/68**; **H01R 23/70**; **G06K 7/06**

IPC 8 full level  
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US5636999A; EP0687035A3; CN105025129A; CN111043952A; FR2747847A1; US6053748A; CN1117417C; EP0860904A3; WO9739418A1

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